

## PIN diode

### RN739F / RN739D

#### ● Applications

VHF / UHF band variable attenuators and AGC

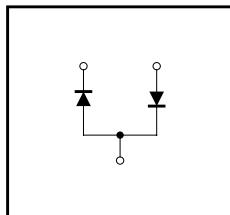
#### ● Features

- 1) Multiple diodes in one small surface mount package.  
(UMD3, SMD3)
- 2) Low high-frequency forward resistance ( $r_F$ ) / low capacitance ( $C_T$ ).
- 3) High reliability.

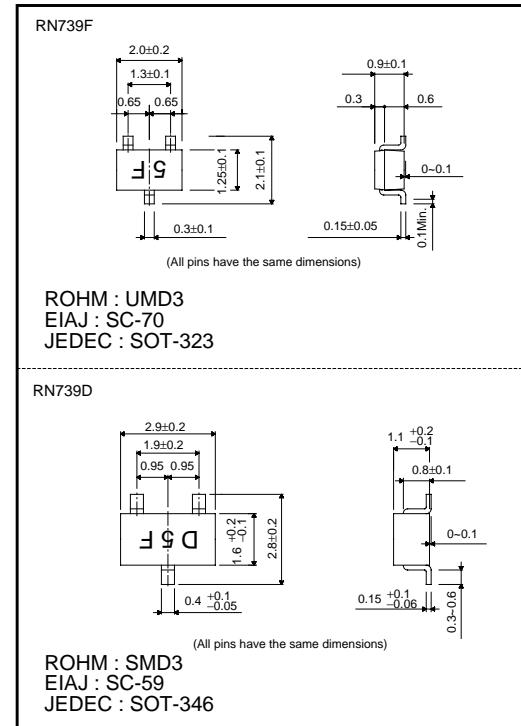
#### ● Construction

Silicon diffusion junction

#### ● Circuit



#### ● External dimensions (Units : mm)



#### ● Absolute maximum ratings ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Limits	Unit
DC reverse voltage	$V_R$	50	V
DC forward current	$I_F$	50	mA
Power dissipation	$P_d$	100	mW
Junction temperature	$T_j$	125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55~+125	$^\circ\text{C}$

#### ● Electrical characteristics ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	$V_F$	—	—	1.0	V	$I_F=50\text{mA}$
Reverse current	$I_R$	—	—	100	nA	$V_R=50\text{V}$
Capacitance between terminals	$C_T$	—	—	0.4	pF	$V_R=35\text{V}, f=1\text{MHz}$
Forward operating resistance	$r_F$	—	—	7	$\Omega$	$I_F=10\text{mA}, f=100\text{MHz}$

## Diodes

### ● Electrical characteristic curves ( $T_a = 25^\circ\text{C}$ )

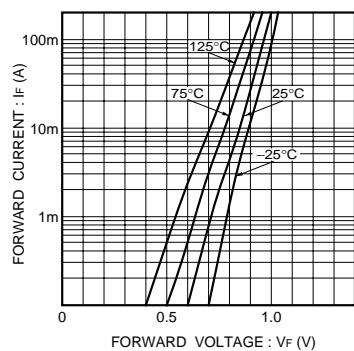


Fig.1 Forward characteristics

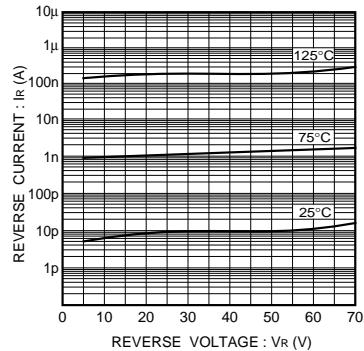


Fig.2 Reverse characteristics

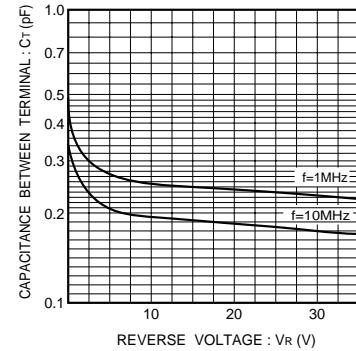


Fig.3 Capacitance between terminals characteristics 1

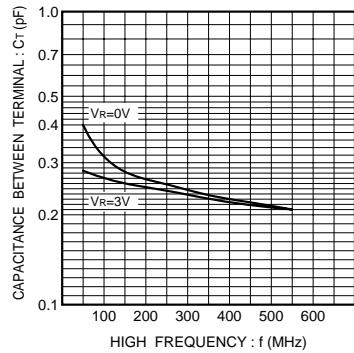


Fig.4 Capacitance between terminals characteristics 2

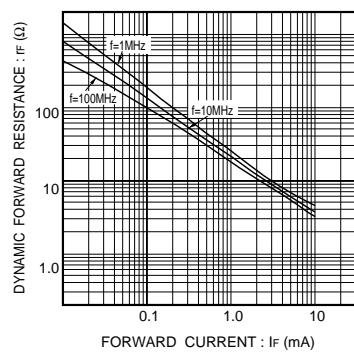


Fig.5 High frequency characteristics

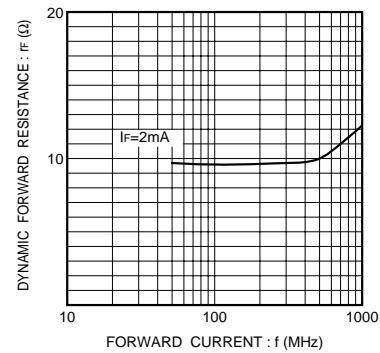


Fig.6 Forward operating resistance characteristics

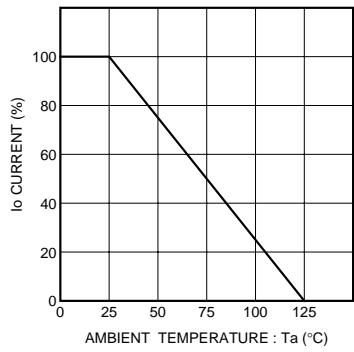


Fig.7 Derating curve  
(mounting on glass epoxy PCBs)